

NON-PROVISIONAL APPLICATION FOR U. S. PATENT UNDER 37 CFR 1.53(b)

TRANSMITTAL FORM

Attorney Docket No.	TI-32857	
Assistant Commissioner for	Patents	
Washington D C 20231		

Sir:

Transmitted herewith for filing is the patent application of:

"EXPRESS MAILING" Mailing Label No. EL881899552US. Date of Deposit: January 30, 2002. I hereby certify that this paper is being deposited with the U.S. Postal Service, Express Mail Post Office to Addressee Service under 37 CFR 1.10 on the date shown above and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Lisa Lynch

Inventor(s):

Baldonado, et al.

For:

METHOD AND SYSTEM OF WIRE BONDING USING INTERPOSER PADS

Enclosed are:

6 Sheets of informal drawings and 11 pages of Specification (including Abstract)

X A Declaration/Power of Attorney (unsigned)

Assignment with PTO Form 1595

This application claims priority of U.S. Provisional Patent Application No. 60/343,652 filed on December 28, 2001 entitled "Method and System of Wire Bonding Using Interposer Pads," and the teachings are incorporated herein by reference.

FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 740.00
Total Claims	21	-20 =	1	X \$18 =	18.00
Independent Claims	3	- 3 =	0	X \$84 =	0.00
Total Filing Fee					\$758.00

Please charge Deposit Account No. 20-0668 in the amount of the total fees set forth. The Assistant Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 20-0668.

All correspondence related to this application may be addressed to Mike Skrehot, at Texas Instruments

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Date

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